Performance of a TPC with Triple GEM and Pixel Readout at long drift distances

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GEFÖRDERT VOM

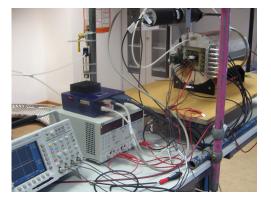


Bundesministerium und Forschung





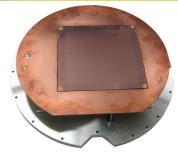


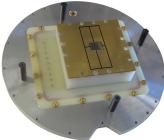


- Field cage designed and produced in Aachen
 - 26 cm diameter
 - 26 cm drift distance
 - Low material budget: 1 % X₀
 - $\bullet\,$ Drift field up to 1 kV/cm
 - Fits into 5 T magnet at DESY
- Trigger for cosmic muons: Scintillators above and below the chamber
 - Veto circuit: Only one shutter window per recorded frame
- TimePix readout with Muros and PixelMan



Gas Amplification and Readout







- Triple-GEM stack
- 1 mm transfer gaps and induction gap
- 390 V across each GEM
- Transfer field 2500 V/cm
- Induction field 3000 V/cm
- TimePix
 - 256 \times 256 Pixel²
 - 55 \times 55 μm^2 pixel size
 - Active area $14 \times 14 \text{ mm}^2$
- Single chip board Modified Freiburg design to glue board into readout plane from the back
- 4 large pads, connected to preamps and oscilloscope

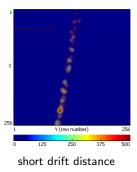


Measurements with Cosmics

More than 40,000 tracks in 1 month of data taking

TimePix operated in "Mixed Mode": Chequerboard pattern with pixels alternating in

- Time Mode
- Time-Over-Threshold Mode proportional to charge



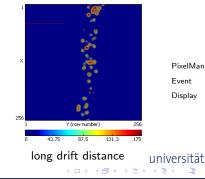


Cluster recorded in mixed mode

- Red: Time
- Blue to green: Charge



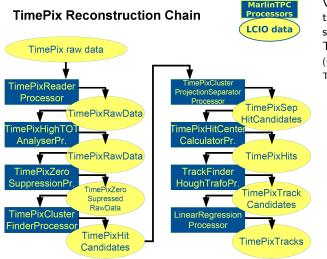
- $\bullet~\text{Gas:}~\text{Ar}/\text{CO}_2~70/30$
- Drift field: 500 V/cm
- GEM voltages: 390 V
- Transfer fields: 2500 V/cm
- Induction field: 3000 V/cm



Reconstruction and Analysis: MarlinTPC

MarlinTPC is the TPC simulation, digitisation, reconstruction and analysis package for the Marlin framework





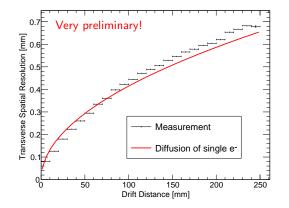
Very modular with more than 50 processors, suited for all kinds of TPC readout (GEMs/Micromegas, ADCs, TDCs, TimePix)

- Reader for TimePix data from PixelMan
- Complete TimePix reconstruction chain
- Analysis processors (e. g. to determine spatial resolution)
- TimePix digitisation

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Current interpretation:

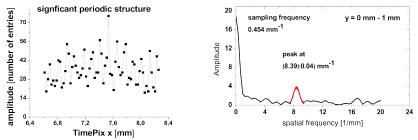
- Short drift distances: Multi-electron clusters
- Long drift distances: Single-electron clusters?

To be confirmed!

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- Fourier transform: Period is 119 ± 6 μm (GEM pitch in x-projection is 120 μm)
- Signal only shows up in first millimetre
- For larger drift distances signal is smeared out due to diffusion

- Drift gap 6 mm
- Transfer gaps 2 mm each
- Induction gap 1 mm

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GEM structure measured in Bonn

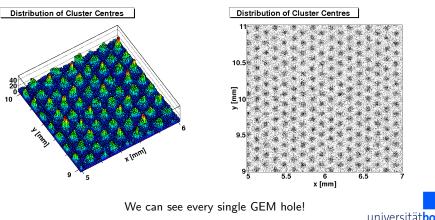
- Dedicated high statistics run with ⁹⁰Sr source untriggered, no *z* information available
- Long drift distance ${\approx}25~{\rm cm}$
- GEM spacing: 1 mm transfer gaps and induction gap







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- Long drift distance ${\approx}25~{\rm cm}$
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Current interpretation:

Spatial separation of the electrons originating from multiple-electron clusters occurs due to the transverse diffusion.

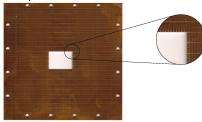
- Very small drift distances: All electrons of a primary cluster pass through the same GEM hole, GEM structure shows up
- Medium drift distances: Electrons of a primary cluster pass through neighbouring GEM holes, GEM structure is washed out
- Long drift distances: Individual electrons can be separated, GEM structure shows up

Problems with this interpretation:

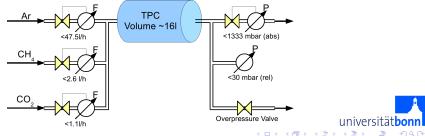
- Number of reconstructed clusters at large drift distances is smaller than expected number of primary electrons (about 1/3)
 - Attachment?
 - Low single electron efficiency?
 - Do reconstructed clusters contain only single electrons?

Next Steps

• Combined readout: Pad plane with 256 pads, $1 \times 4 \text{ mm}^2 + \text{TimePix}$



• Gas system to mix gases and keep pressure constant



Post-Processing of TimePix

Freiburg group is testing MediPix chips with enlarged pixels ($110 \times 110 \ \mu m^2$), post-processed on per chip level by FMF (Freiburger Metallforschungszentrum)

Bonn has established first contact with IZM: Institut für Zuverlässigkeit und Mikrointegration, Berlin

Post-Processing of TimePix chips — on wafer level:

- Enlarging pixel size by adding metal pads on a passivation
- Silicon through vias: replacing wire bonds by bump bonds
- InGrid plans to learn technology from Twente University

Contributions to the development of a TimePix successor chip.

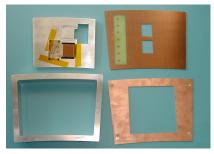


Institut Zuverlässigkeit und Mikrointegration

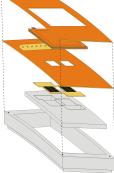


LP Module with 3GEM + TimePix

- $\bullet~3$ standard GEMs 10 $\times~10~\text{cm}^2$
- 1 mm transfer gaps and induction gap
- Two quad-boards (NIKHEF) with 4 TimePix chips each



anode plane GEMs readout plane quad-boards reinforcement of anode plane redframe



• Currently testing quad-board





Summary and Outlook



TPC with 3GEM + TimePix readout

- Over 40,000 cosmic track recorded
- Individual GEM holes can be resolved
- Full TimePix support in MarlinTPC

Plans

- Combined pads + TimePix readout
- Wafer post-processing of TimePix

End of this Month:

• Test beam with 3 GeV electron beam from ELSA in Bonn High statistics z-scans

End of this Year:

• Measurements at EUDET large prototype